OMRON

Ultra-low Profile Dome Key

B3D

Single-key Type Added to Series of B3DA Ultra-low Profile Dome Arrays

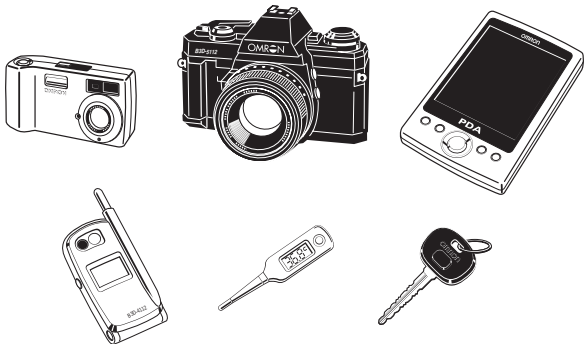
- No soldering required.
  Attach directly to PCB to make an ultra-low profile tactile switch.
  Construction provides strong resistance to static electricity by having no soldered terminals.
- Matrix adhesive used to create highly dust-proof construction with good ventilation.
- Lower profile, lighter weight, and crisp clicking action achieved using stainless steel contact dome.
- OMRON's unique circular contact action ensures a high level of resistance to foreign matter.

NEW

Application Examples

Use Dome Keys for the operating parts on various electronic devices that require low-profile controls, as follows:

- Operating switches with few mounted parts above PCBs.
  (Example: Camera operating buttons)
- Small orders, where initial investment in Dome Arrays is not feasible.
  (Example: Trial applications, commercial equipment, etc.)
- Applications requiring a single key only.
  (Example: Reset buttons)

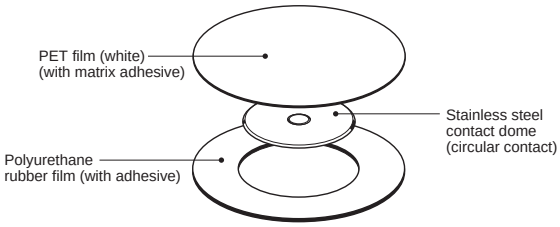


Specifications

Item / Model	B3D-4112	B3D-5112
Diameter of contact dome	4-mm dia.	5-mm dia.
Operating force (OF)	1.67±0.49 N	
Releasing force (RF)	0.2 N min.	
Pretravel (PT)	0.2±0.1 mm	
Thickness	0.3±0.1 mm	
Life expectancy	500,000 operations min.	1,000,000 operations min.
Switching capacity	12 VDC, 10 mA (resistive load) (recommended minimum load: 3 VDC, 1 mA (resistive load)	
Ambient operating temperature	−40 to 80°C	
Ambient storage temperature	−40 to 85°C	
Contact dome	Stainless steel	
Plating	Silver	

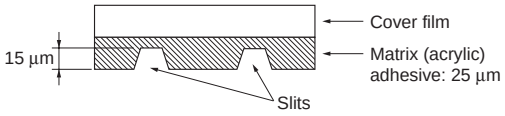
Note: The Dome Keys are sold in units of 500 (20 sheets, with 25 Dome Keys per sheet). Orders must be made in multiples of 500 Dome Keys.

Structure



Matrix Adhesive

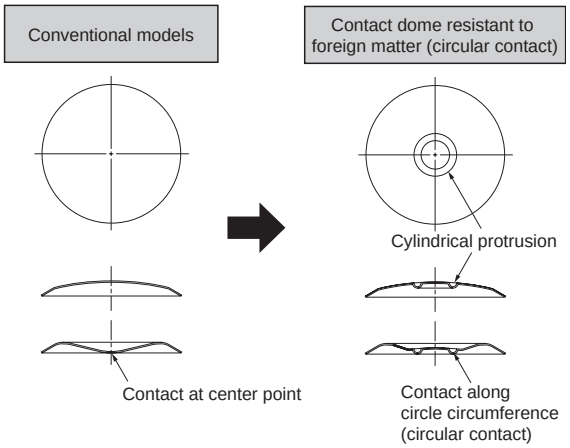
The surface structure of this adhesive has grid-shaped slits, as shown in the following cross-sectional diagram. These slits provide both ventilation and dust-proofing, which is required for contact dome operation.



Circular Contact

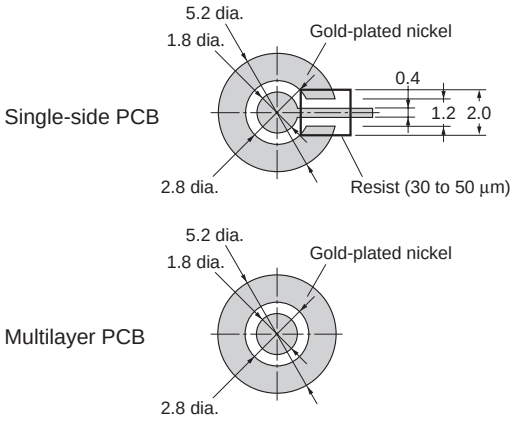
When contact dome keys are attached to the PCB, any PCB dust or foreign particles will tend to collect in the center of the key when it is pressed. Therefore, poor contact occurs easily in keys that provide contact at the center point only.

The circular contact construction provides contact along the circumference of a circle, thus preventing poor contact by avoiding the center point.

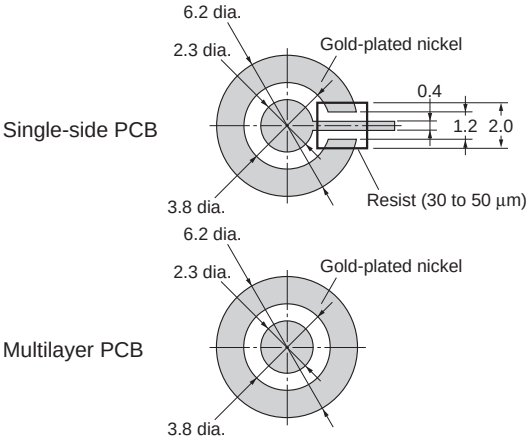


Recommended Contact Form

4-mm Diameter Contact Dome (B3D-4112)

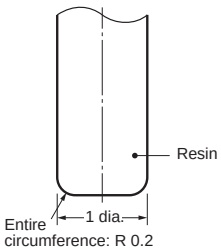


5-mm Diameter Contact Dome (B3D-5112)

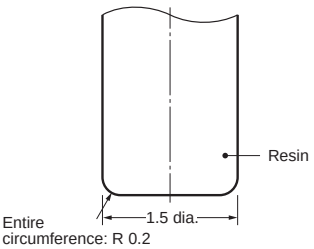


Recommended Operating Part Form

4-mm Diameter Contact Dome (B3D-4112)

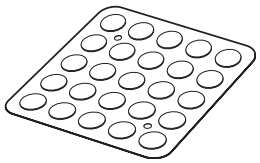


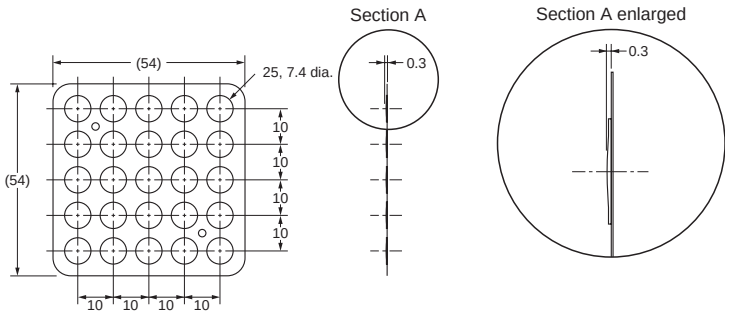
5-mm Diameter Contact Dome (B3D-5112)



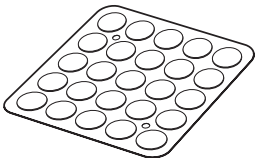
Dimensions

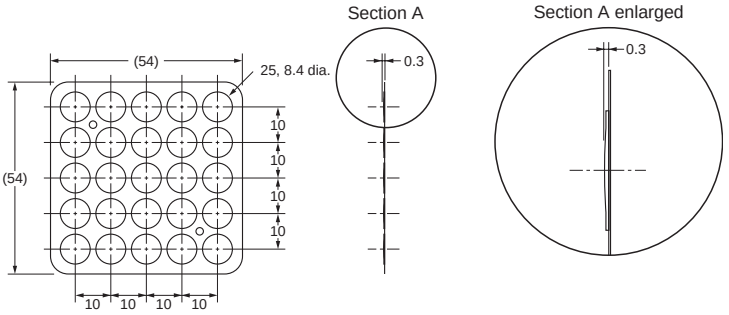
B3D-4112





B3D-5112





Precautions

■ Correct Use

Note: Be sure to read the *Industrial Components General Catalog* (Y202) before using the Dome Keys for general precautions.

■ Attaching to the PCB

Remove the Dome Key from the sheet using tweezers or a vacuum pick-up tool, and attach it above the contact on the PCB surface, which has been wiped clean in advance. Press down on the top surface using an elastic material, such as urethane rubber, and a force of 2.94 to 4.9 N. Place a positioning mark (circle) on the PCB for easy positioning.

Make sure that the position of the Dome Key is aligned correctly before use. Significant misalignment may result in short-circuits or reduced sensitivity.

Note: The recommended vacuum pick-up tool is the Hozan P-835 Vacuum Pick with an M suction pad (7-mm dia.).

Do not reuse a B3D Dome Key that has been detached from the PCB. Attach a new Dome Key to the PCB.

Do not touch the contact dome with bare hands, or with unclean gloves. Doing so may damage the contact dome, which is the part that comes in contact with the PCB.

■ Reflow Soldering

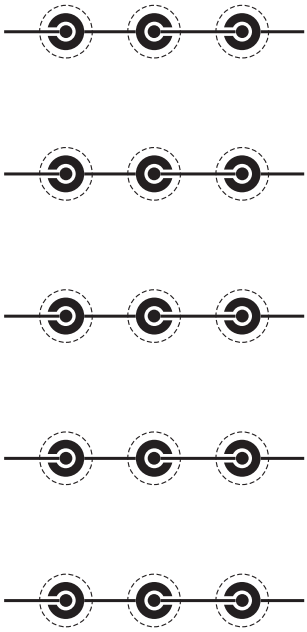
The Dome Key cannot withstand heat from reflow soldering. Always perform reflow soldering before attaching the Dome Key to the PCB.

■ Washing

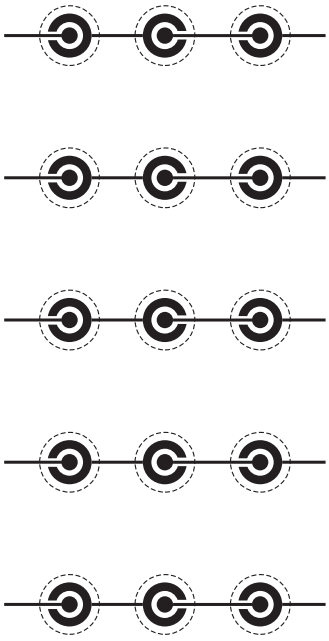
Do not wash the Dome Key. The Dome Key is not water-resistant and must not be exposed to water or other liquids.

PCB Pattern Diagrams (Full scale)

■ **B3D-4112**



■ **B3D-5112**



ALL DIMENSIONS SHOWN ARE IN MILLIMETERS.
To convert millimeters into inches, multiply by 0.03937. To convert grams into ounces, multiply by 0.03527.

Cat. No. A158-E1-01 **In the interest of product improvement, specifications are subject to change without notice.**

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Printed in Japan
0803-?M (0803) (?)

Safety Precautions

■ Precautions for Safe Use

Use the Switch within the rated voltage and current ranges, otherwise the Switch may have a shortened life expectancy, radiate heat, or burn out. This particularly applies to the instantaneous voltages and currents when switching.

■ Precautions for Correct Use

Storage

To prevent degradation, such as discoloration, in the terminals during storage, do not store the Switch in locations that are subject to the following conditions.

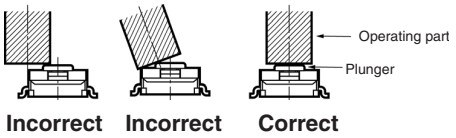
1. High temperature or humidity
2. Corrosive gases
3. Direct sunlight

Handling

1. Operation

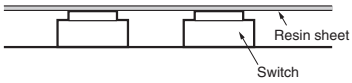
Do not repeatedly operate the Switch with excessive force. Applying excessive pressure or applying additional force after the plunger has stopped may deform the disc spring of the Switch, resulting in malfunction. In particular, applying excessive force to Side-operated Switches may damage the caulking, which in turn may damage the Switch. Do not apply force exceeding the maximum (29.4 N for 1 minute, one time) when installing or operating Side-operated Switches.

Be sure to set up the Switch so that the plunger will operate in a straight vertical line. A decrease in the life of the Switch may result if the plunger is pressed off-center or from an angle.



2. Dust Protection

Do not use Switches that are not sealed in dust-prone environments. Doing so may cause dust to penetrate inside the Switch and cause faulty contact. If a Switch that is not sealed must be used in this kind of environment, use a sheet or other measure to protect it against dust.



PCBs

The Switch is designed for a 1.6-mm thick, single-side PCB.

Using PCBs with a different thickness or using double-sided, through-hole PCBs may result in loose mounting, improper insertion, or poor heat resistance in soldering. These effects will occur, depending on the type of holes and patterns of the PCB. Therefore, it is recommended that a verification test is conducted before use.

If the PCBs are separated after mounting the Switch, particles from the PCBs may enter the Switch. If PCB particles or foreign particles from the surrounding environment, workbench, containers, or stacked PCBs become attached to the Switch, faulty contact may result.

Soldering

1. General Precautions

Before soldering the Switch on a multilayer PCB, test to confirm that soldering can be performed properly. Otherwise the Switch may be deformed by the soldering heat on the pattern or lands of the multilayer PCB.

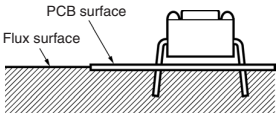
Do not solder the Switch more than twice, including rectification soldering. An interval of five minutes is required between the first and second soldering.

2. Automatic Soldering Baths (B3F, B3W, B3WN, B3M, B3J)

Soldering temperature: 260°C max.
Soldering time: 5 s max. for a 1.6-mm thick single-side PCB

Preheating temperature: 100°C max. (ambient temperature)
Preheating time: Within 60 s

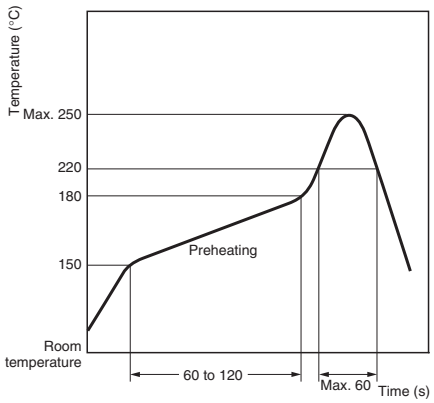
Make sure that no flux will rise above the level of the PCB. If flux overflows onto the mounting surface of the PCB, it may enter the Switch and cause a malfunction.



3. Reflow Soldering (Surface Mounting)

Solder the terminals within the heating curve shown in the following diagram.

B3S, B3SN, B3FS



Note: The above heating curve applies if the PCB thickness is 1.6 mm.

The peak temperature may vary depending on the reflow bath used. Confirm the conditions beforehand.

Do not use an automatic soldering bath for surface-mounted Switches. The soldering gas or flux may enter the Switch and damage the Switch's push-button operation.

4. Manual Soldering (All Models)

Soldering temperature: 350°C max. at the tip of the soldering iron
Soldering time: 3 s max. for a 1.6-mm thick, single-side PCB

Before soldering the Switch on a PCB, make sure that there is no unnecessary space between the Switch and the PCB.

Washing

1. Washable and Non-washable Models

Washable (sealed types)	B3W, B3WN, B3S, B3SN
Non-washable (standard types)	B3F, B3FS, B3M, B3J, B3DA, B3D

Standard Switches are not sealed, and cannot be washed. Doing so will cause the washing agent, together with flux or dust particles on the PCB, to enter the Switch, resulting in malfunction.

2. Washing Methods

Washing equipment incorporating more than one washing bath can be used to clean washable models, provided that the washable models are cleaned for one minute maximum per bath and the total cleaning time does not exceed three minutes.

3. Washing Agents

Apply alcohol-based solvents to clean washable models. Do not apply any other agents or water to clean any washable model, as such agents may degrade the materials or performance of the Switch.

4. Washing Precautions

Do not impose any external force on washable models while washing.

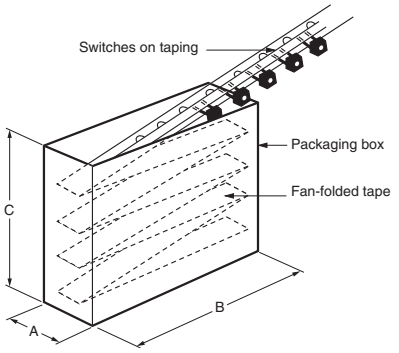
Do not clean washable models immediately after soldering. The cleaning agent may be absorbed into the Switch through respiration as the Switch cools. Wait for at least three minutes after soldering before cleaning washable models.

Do not use Sealed Switches while submersed in water or in locations exposed to water.

Switch Packaging (Taping Specification Models)

1. Radial Types

The tape is packaged by fan-folding into the box, as shown in the following diagram.



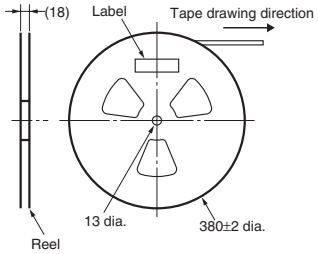
Model	A	B	C
B3F	50 mm	325 mm	275 mm
B3WN	53 mm	326 mm	350 mm

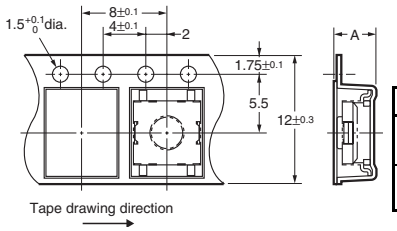
Do not apply any external force to the packaging box, or subject it to vibration. Doing so may deform the Switch terminals.

Remove the tape slowly, making sure that the Switches are not entangled or caught. Otherwise the terminals may be deformed.

Do not store the packaged Switches in locations subject to high temperatures or high humidity. The packaging boxes are sealed with paper tape and are not airtight. Storing the packaged Switches in locations with high temperature or high humidity may result in deterioration of the tape and Switches, and long-term storage under such conditions may cause discoloration of the Switch terminals.

2. Packaging Specifications for Embossed Taping (B3FS-1000P/-1002P, B3SN)



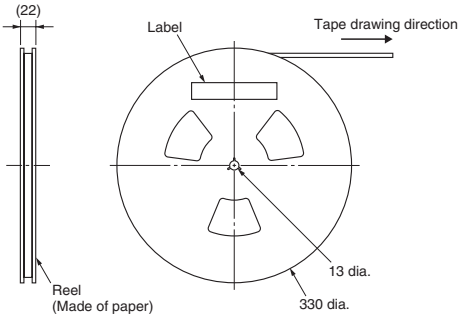


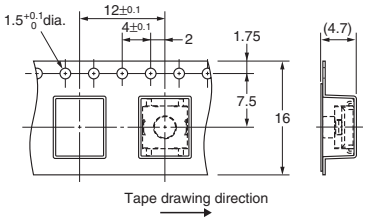
Model	A
B3FS-1000P B3FS-1002P	3.9 mm
B3SN	3.6 mm

Standards	Conforms to JEITA.
Package	3,000 Switches
Heat resistance	50°C for 24 hours (without deformation)

Note: Switches with ground terminals are packaged with the ground terminal on the opposite side of the guide hole.

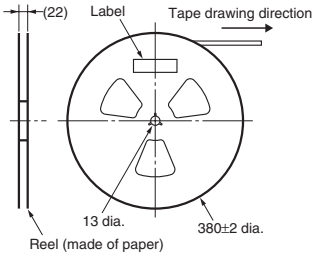
B3FS-1010P

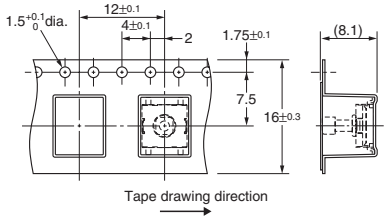




Standards	Conforms to JEITA.
Package	1,000 Switches
Heat resistance	60°C for 24 hours (without deformation)

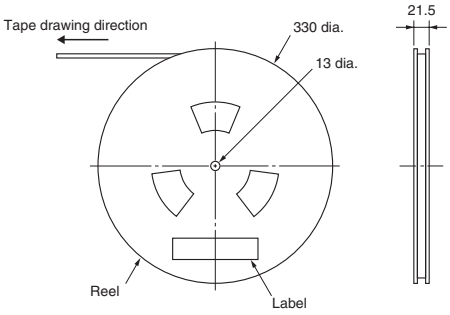
B3FS-1050P

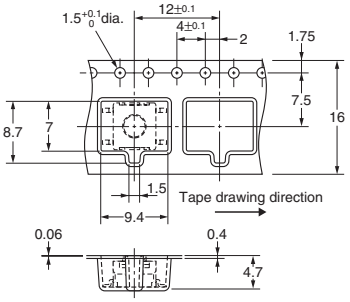




Standards	Conforms to JEITA.
Package	1,000 Switches
Heat resistance	60°C for 24 hours (without deformation)

B3S





Standards	Conforms to JEITA.
Package	1,000 Switches
Heat resistance	50°C for 24 hours (without deformation)

Note: Switches with ground terminals are packaged with the ground terminal on the opposite side of the guide hole.

LEDs (B3J)

Make sure that the polarity of the LEDs is correct. The polarity is not indicated on the Switch, but the positive pole is located on the back surface of the Switch on the side without the OMRON mark.

Connect limiting resistors to the LEDs. The Switch does not have built-in limiting resistors, so satisfy the LED characteristics by obtaining the limiting resistance according to the following formula based on the voltage to be used.

$$\text{Limiting resistance (R)} = \frac{\text{(Voltage used (E) – LED forward voltage (VF))}}{\text{LED forward current (IF)}}\ (\Omega)$$